

WE CLAIM:

1. A heat dissipating device for dissipating heat generated by an electronic component mounted on a circuit board inside a housing, the housing having opposite first and second walls, one of which is formed with a through hole, said heat dissipating device comprising:

a heat-conducting unit adapted to be disposed in the housing, said heat-conducting unit having a first heat-conducting member adapted to be mounted on the circuit board and adapted to contact and to be in thermal communication with the electronic component, and a second heat-conducting member that has a first end portion connected to said first heat-conducting member, and a second end portion opposite to said first end portion and extending outwardly of the housing through the through hole in said one of the first and second walls; and

a heat-dissipating fin module adapted to be mounted on said one of the first and second walls externally of the housing, said heat-dissipating fin module having a base plate connected to and in thermal communication with said second end portion of said second heat-conducting member of said heat-conducting unit, and a plurality of fin posts mounted fixedly and spacedly on and in thermal communication with said base plate.

2. The heat dissipating device as claimed in Claim 1, further comprising a thermal insulating member adapted

to be retained between said heat-dissipating fin module and said one of the first and second walls of the housing.

3. The heat-dissipating device as claimed in Claim 2, wherein said thermal insulating member is a thermal
5 insulating plate that is formed with a mounting hole corresponding to the through hole in said one of the first and second walls of the housing for receiving said second end portion of said second heat-conducting member.

10 4. The heat dissipating device as claimed in Claim 1, wherein said first heat conducting member includes a mounting plate adapted to be mounted on the circuit board and adapted to contact and to be in thermal communication with the electronic component, a plurality of
15 heat-dissipating fin plates mounted on said mounting plate, and a heat pipe having a first section mounted on said mounting plate, and a second section opposite to said first section and extending to said second heat-conducting member.

20 5. The heat dissipating device as claimed in Claim 4, wherein said first end portion of said second heating-conducting member is formed with a pipe-receiving groove for receiving said second section of said heat pipe.

25 6. The heat dissipating device as claimed Claim 1, wherein said base plate of said heat-dissipating fin module is formed with a plurality of mounting posts

extending toward said one of the first and second walls of the housing such that said fin posts are spaced apart from the housing when said fin module is mounted on the housing.

5 7. An electronic apparatus comprising:

a housing having opposite first and second walls, one of which is formed with a through hole;

a circuit board disposed in said housing and provided with an electronic component thereon; and

10 a heat dissipating device for dissipating heat generated by said electronic component, said heat dissipating device including

a heat-conducting unit disposed in said housing, said heat-conducting unit having a first
15 heat-conducting member mounted on said circuit board and contacting and in thermal communication with said electronic component, and a second heat-conducting member that has a first end portion connected to said first heat-conducting member, and a second end portion
20 opposite to said first end portion and extending outwardly of said housing through said through hole in said one of said first and second walls, and

a heat-dissipating fin module mounted on said one of said first and second walls externally of said housing,
25 said heat-dissipating fin module having a base plate connected to and in thermal communication with said second end portion of said second heat-conducting member

of said heat-conducting unit, and a plurality of fin posts mounted fixedly and spacedly on and in thermal communication with said base plate.